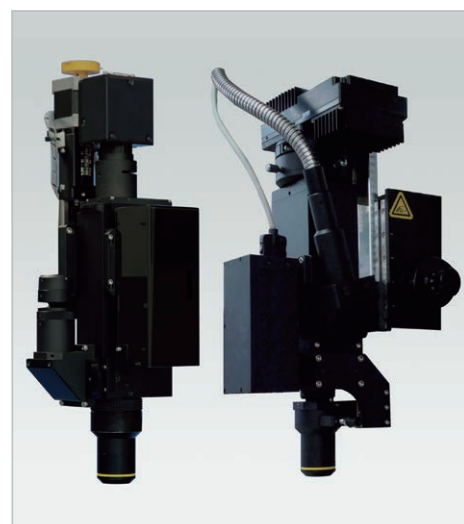


Laser Auto Focusing Unit

MS-200-TWL-LAF

Sampling rate is 10 times faster than our conventional products by using upgraded laser. Using diagonal line laser is not interfered by pattern on sample. This auto focusing unit is ideal for the surface inspection of samples with high-reflection rate, such as wafer or glass. Options include compatibility with differential interference contrast (DIC) and observation of up to 3 wavelengths.



Laser Specification

Model	LAF5S-C
Laser type	Semiconductor laser
Output wavelength	670nm
Safety standard	3R
Sampling rate	Max. 5kHz
Positioning time	External trigger: 0.2sec Tracking: 0sec

PC Environment

OS	Windows 7 (32bit & 64bit) Windows 8 (32bit & 64bit)
CPU	Intel core i5 or later
HDD	120GB or more

Z axis specification

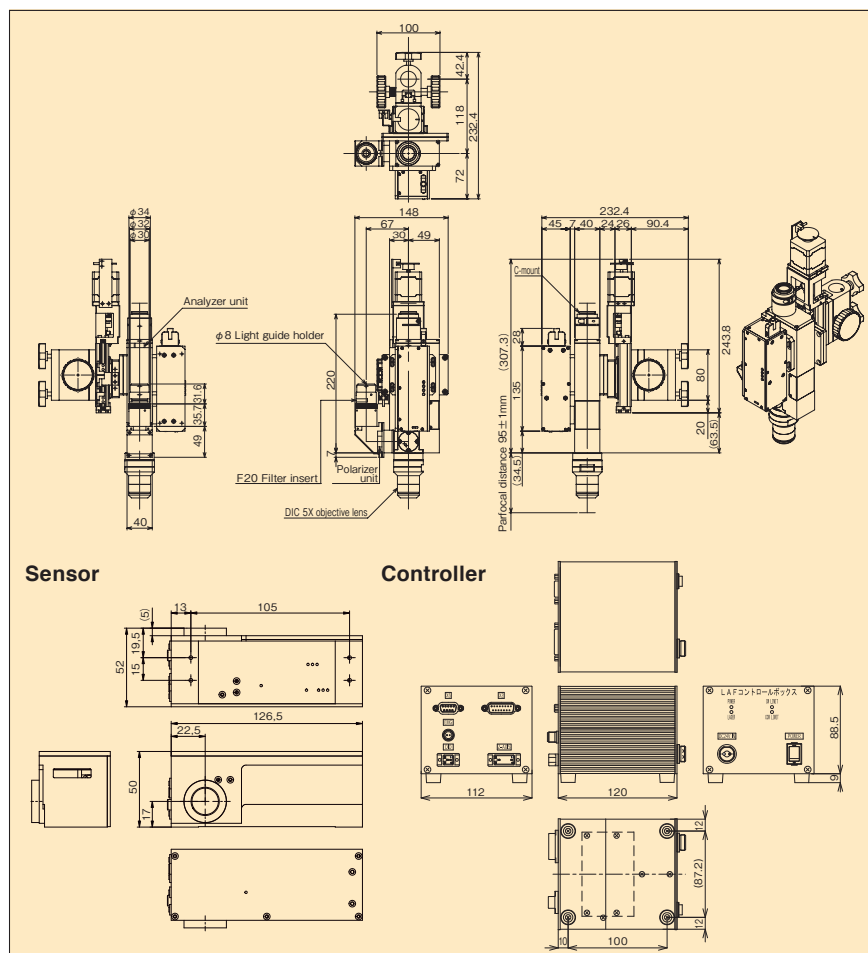
Stepping motor driver is compatible both with CW/CCW pulse output or DIR/PULSE output.

<Standard specification>

Resolution: 0.1 μ m
Stroke:
Ultra compact type +/-2.5mm
Compact type: +/-5mm
Standard type: +/-15mm

Laser Type

Model	Laser wavelength	Laser beam shape
LAF5S-C	670nm	45 degree diagonal



System Diagram

